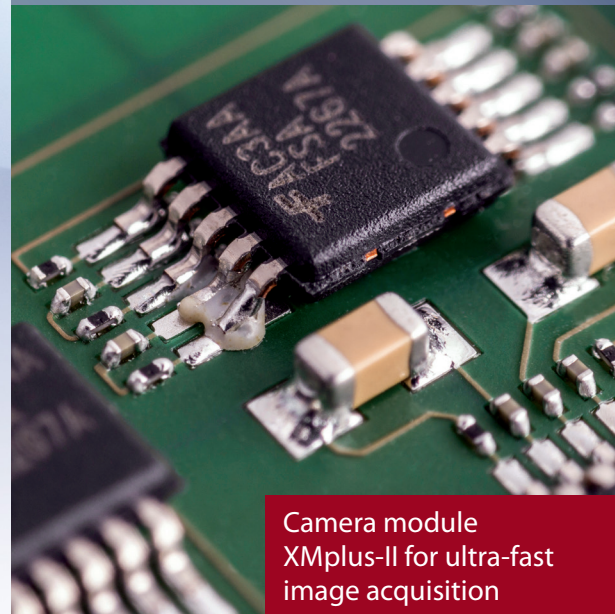




Exceptional
3D Computing
Power and Reliable
Measurement
Accuracy

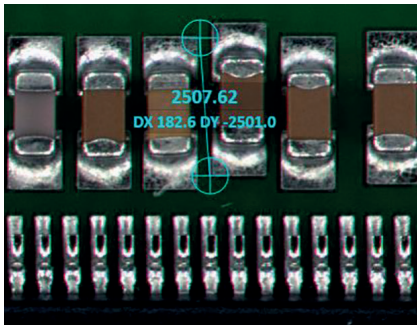


Camera module
XMplus-II for ultra-fast
image acquisition

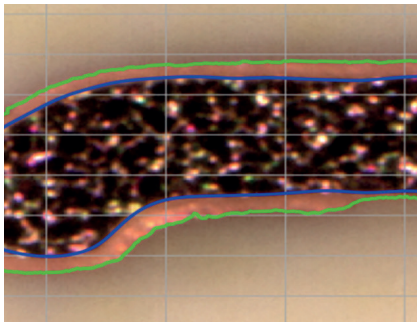
iS6059 PCB Inspection Plus

Smart networked automatic optical
inspection of complex assemblies

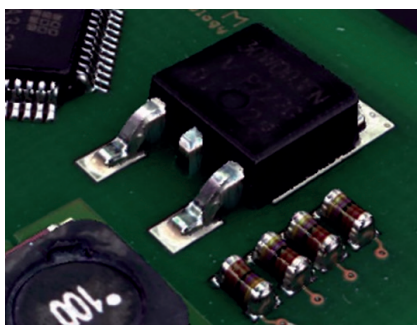
Line-Integrated Quality Control for Highest Requirements



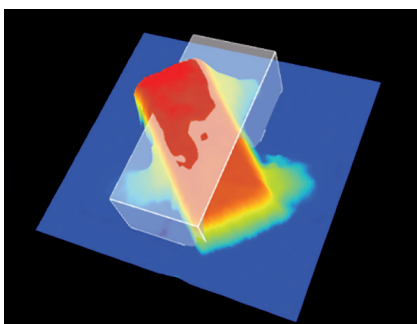
Simple measurement of standards and exceptional cases



Inspection of cut voids using a combined 2D, 2½D and 3D approach



Complete rendering with 360View for verification tasks



Component body detection using 3D methods

Uncompromisingly good imaging thanks to state-of-the-art sensor technology

High resolution for precise inspection of microscopic components

Large tilted views for the most accurate analyses

Smart verification with optional AI integration

Intuitively simple operation and creation of inspection programs

Fast data processing with powerful frame grabber

Extremely fast handling of the inspection objects

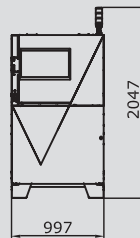
Competent service worldwide – online, by phone, and on site

Electronic products must function reliably and often meet very high safety requirements. Quality and durability are crucial. Against this background, first-class 3D and software features, high measurement accuracy, and exceptional image quality are expected from an automatic optical inspection system – as well as a very robust construction. When producing for a variety of customers and markets, simple programming and flexible handling are particularly important. In such cases, it is necessary to cover different products in small or large production quantities flexibly while still being able to quickly and comprehensively detect any manufacturing defects. In the case of very large quantities, throughput is particularly important. Viscom takes these and other considerations into account in the development of new inspection systems.

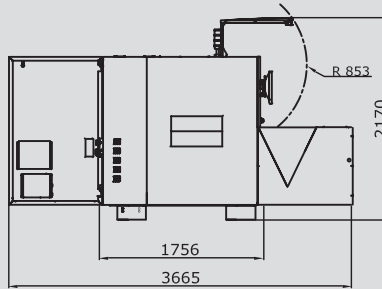
Technical Specifications



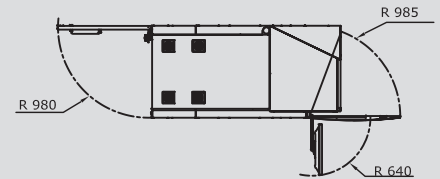
Front view



Side view



Top view



Dimensions in mm

iS6059 PCB Inspection Plus		
Inspection scope		Solder joints, mounting, open surfaces, character recognition, solder paste, mold, assembly
Camera technology		XMplus-II
	Total number of megapixels	Up to 150
	3D sensor technology	
	Z-resolution	0.5 µm
	Z-range	Up to 30 mm (1.2")
	Angled view cameras	
	Number of megapixel cameras	8
	Orthogonal camera	
	Resolution	20.4 µm/Pixel +/-1% (binning); 10.2 µm/Pixel +/-1%
	Field of view	50 mm x 50 mm (2" x 2")
Inspection speed		Up to 80 cm ² /s
Software	User interface	Viscom vVision/Sl EasyPro
	Statistical process control	Viscom vSPC/SPC, open interface (optional)
	Verification station	Viscom vVerify/HARAN
	Remote diagnosis	Viscom SRC (optional)
	Programming station	Viscom PST34 (optional)
System computer	Operating system	Windows®
	Processor	Intel®Core™i9
PCB handling	PCB dimensions	508 mm x 508 mm (20" x 20")
	PCB support	Optional
	Transport height	850 - 950 mm ± 20 mm (33.5" - 37.4" ± 0.8")
	Width adjustment	Automatic
	Transport concept	Single-track transport system
	PCB clamping	Pneumatic
	Upper transport clearance	50 mm (2")
	Lower transport clearance	50 mm (2"), other heights on request
Other system data	Positioning unit	Synchronous linear motor
	Interfaces	SMEMA, SV70, Hermes, CFX
	Power requirements	230/400 V, 50/60 Hz, 3P/N/PE +/- 10 %, 4 - 6 bar working pressure
	System dimensions	997 mm x 1756 mm x 1876 mm (39.3" x 69.1" x 73.9") (W x H x D)
	Weight	Approx. 1070 kg (2359 lbs)

Our international subsidiaries and representatives can be found at:

www.viscom.com